IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	© Copyright 2005. IPC,	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both This docum level parts,	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materials and Mfg Information								
upplier Inform	nation												
Company name*			Company unique ID			Unique ID Authority				Response Date*			
nsemi									2024-05-18				
ontact Name			Title - Contact			Phone - Contact*			Email - Contact*				
Product-Env-Stewa	ards		Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Item		Number Mfr Item Name			Effective	e Date	Version	Manufacturing Site		Weight*	UOM	Unit Type
		FNC42060F2-ZA02 SPM451		SPM45H INV 600	OV 20A LL Fulfill Pin Hole	2024-05-	-18		СРА	1	11113.298	mg	Each
	Process Information		. 15		GTD 020 MGL D	D 1	D	D 1 T	W 75 (P. 1)			CD C	,
8					-STD-020 MSL Rating	Peak Process Body Temperature Max Time at F							
•	n (Sn) - annealed	C	U Alloy	N	NA .	0		<u> </u>	30	secon	ds 3		
omments													
For more informati	on regarding material con	nposition p	lease refer to	page 3									

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	37.4431	mg	Supplier	Silicon (Si)	7440-21-3		37.4431	mg
Die Attach	2.3868	mg	Supplier	Silver (Ag)	7440-22-4		1.7901	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.5967	mg
Die Attach Solder	43.092	mg	Supplier	Silver (Ag)	7440-22-4		1.0773	mg
			A	Lead (Pb)	7439-92-1	7a	39.8601	mg
			Supplier	Tin (Sn)	7440-31-5		2.1546	mg
Heat Sink Attach	23.1894	mg	Supplier	Dicyandiamine	461-58-5		1.6233	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.8552	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		19.711	mg
Lead Frame	3510.64	mg	Supplier	Silver (Ag)	7440-22-4		884.6813	mg
			Supplier	Copper (Cu)	7440-50-8		2625.9585	mg
Mold Compound-Black	6269.7	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		250.788	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		250.788	mg
			Supplier	Carbon Black (C)	1333-86-4		31.3485	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5423.2905	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		62.697	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		250.788	mg
Plating	60.7986	mg	Supplier	Tin (Sn)	7440-31-5		60.7986	mg
Substrate	1138.32	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1104.1704	mg
			Supplier	Silicon Dioxide (SiO2)	99493-55-7		11.3832	mg
			Supplier	Cobalt Oxide (CoO)	1307-96-6		11.3832	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7		11.3832	mg
Thermistor	4.4737	mg	Supplier	Silver (Ag)	7440-22-4		0.3579	mg
			Supplier	Tin (Sn)	7440-31-5		0.076	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1		1.1631	mg
			Supplier	Palladium (Pd)	7440-05-3		0.1521	mg
			Supplier	Iron Trioxide (Fe2O3)	1309-37-1		0.0002	mg
			В	Nickel (Ni)	7440-02-0		0.0313	mg
			Supplier	Cobalt Oxide (Co3O4)	1308-06-1		0.7694	mg
1			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7		1.9236	mg

Wire Bond - Al	22.005	mg	Supplier	Aluminum (Al)	7429-90-5	22.005	mg
Wire Bond - Cu	1.2488	mg	Supplier	Copper (Cu)	7440-50-8	1.2488	mg